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U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

	1027/0980 PATENTS UNLT		
	To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof		
	Name of conveying party(ies):	Name and address of receiving party(ies)	
	Yoshiyuki Enomoto (1/21/04) Keishi Inoue (2/2/04)	Name: Sony Corporation	
	Additional name(s) of conveying party(ies) Yes X No	Internal Address: Street Address: 6-7-35 Kitashinagawa Shinagawa-Ku	
	3. Nature of Conveyance:		
	X Assignment Merger		
	Security Agreement Change of Name	City: Tokyo	
	Other	Country: Japan Zip: 141-0001	
	Execution Date: see Box 1, conveying parties	Additional name(s) & Yes X No address(es) attached:	
	Application number(s) or patent number(s):	2-23-04	
	If this document is being filed together with a new application, the ex	xecution date of the new application is: 1 - 1/21/04; 2-2/2/04	
^	A. Patent Application No.(s):	B. Patent No.(s):	
02/27/2004 MKRYPR	SH 00000020 180013 10487440 \		
01 FC:8021	40.00 DA		
	Additional numbers attached? Yes X No / 548744		
	Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved: 1	
	Name: Ronald P. Kananen RADER, FISHMAN & GRAUER PLLC	7. Total fee (37 CFR 3.41) \$ 40.00 Enclosed	
	Street Address: 1233 20th Street, N.W.	x Authorized to be charged to deposit account	
	Suite 501	Authorized to be charged to credit card (Form 2038 enclosed)	
-	Other 7's	8. Deposit account number:	
	City: State: Zip: Washington DC 20036	18-0013	
	(Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.		
	Ronald P. Kananen, Reg. No. 24,104 Name of Person Signing	February 23, 2004 Signature Date	
	Total number of pages including cover sheet, attach	nments, and documents: 3	

PATENT REEL: 015464 FRAME: 0065

Docket	Number:	SON-2785
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.PCT/JP03/0866 International Filing Date: July 8, 2003.

This assignment executed on the dates indicated below.

Yoshiyuki ENOMOTO	Execution date of U.S. Patent Application
Name of first or sole inventor	
Kanagawa, Japan	
Residence of first or sole inventor	
Joshiyuhi Enomoto Signature of first of sole inventor	January 21 2004
Signature of first of sole inventor	Date of this assignment

Keishi INOUE	
Name of second inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of second inventor	
Keishi Inaue	Feb 2, 2004 Date of this assignment
Signature of second inventor	Date of this assignment
Name of third inventor	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this assignment
Name of fourth inventor	Execution date of U.S. Patent Application
Name of fourth inventor	Execution date of O.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment

RECORDED: 02/23/2004

PATENT REEL: 015464 FRAME: 0067